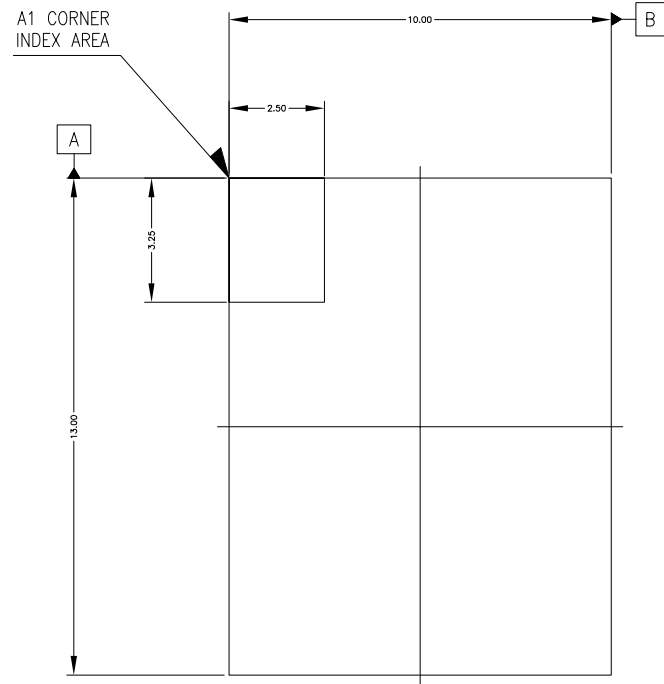
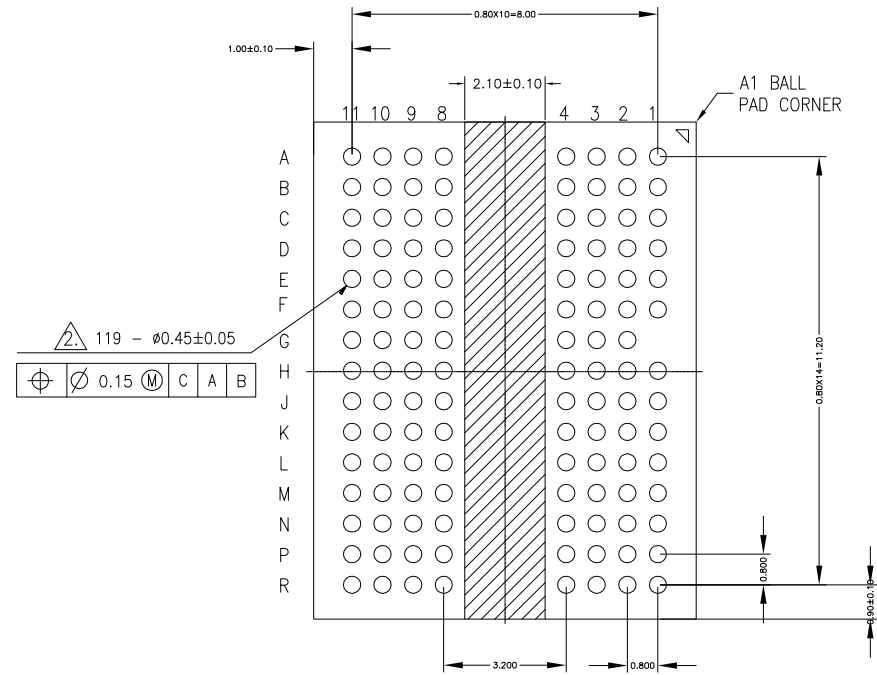


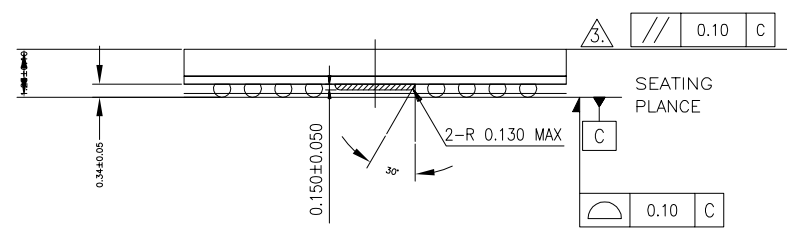
NO	변경 내용



TOP VIEW



BOTTOM VIEW



FRONT VIEW

- Notes>
- All Dimensions are in millimeters.
 - Pre-reflow Solder ball diameter : 0.45 +/- 0.02mm

ATsemicon		TITLE	PACKAGE OUTLINE FBGA, 10 X 13mm 0.80pitch, 119 , 2L			
DES. BY	연구원/남우식	14.03.17	DWG. NO	GP0066		
CHE. BY			REV. NO	UNIT	SCALE	SHEET
DRA. BY			0	MM	1/1	1/1
APP. BY	이사/이우섭	14.03.17				